

# High Speed 8-Bit TTL A/D Converter

# AD9012

### FEATURES

100 MSPS ENCODE Rate Very Low Input Capacitance—16 pF Low Power—1 W TTL Compatible Outputs MIL-STD-883 Compliant Versions Available

APPLICATIONS Radar Guidance Digital Oscilloscopes/ATE Equipment Laser/Radar Warning Receivers Digital Radio Electronic Warfare (ECM, ECCM, ESM) Communication/Signal Intelligence

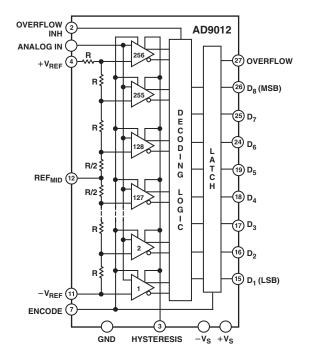
### **GENERAL DESCRIPTION**

The AD9012 is an 8-bit, ultrahigh speed, analog-to-digital converter. The AD9012 is fabricated in an advanced bipolar process that allows operation at sampling rates up to 100 megasamples/second. Functionally, the AD9012 is comprised of 256 parallel comparator stages whose outputs are decoded to drive the TTL compatible output latches.

The exceptionally wide large-signal analog input bandwidth of 160 MHz is due to an innovative comparator design and very close attention to device layout considerations. The wide input bandwidth of the AD9012 allows very accurate acquisition of high speed pulse inputs without an external track-and-hold. The comparator output decoding scheme minimizes false codes, which is critical to high speed linearity.

The AD9012 is available in two grades: one with 0.5 LSB linearity and one with 0.75 LSB linearity. Both versions are

### FUNCTIONAL BLOCK DIAGRAM



offered in an industrial grade, -25°C to +85°C, packaged in a 28-lead DIP and a 28-lead JLCC. The military temperature range devices, -55°C to +125°C, are available in ceramic DIP and LCC packages and are compliant to MIL-STD-883 Class B.

The AD9012 is available in versions compliant with MIL-STD-883. Refer to the Analog Devices *Military Products Databook* or current AD9012/883B data sheet for detailed specifications.

REV. F

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# **AD9012—SPECIFICATIONS ELECTRICAL CHARACTERISTICS** ( $+V_s = +5.0 V$ ; $-V_s = -5.2 V$ ; Differential Reference Voltage = 2.0 V; unless otherwise noted.)

Parameter	Temp	Test Level	1	D9012A Typ	Q/AJ Max	AD Min	99012BQ Typ	)/BJ Max	Al Min	D9012S Typ	Q/SE Max	AI Min	09012T Typ	Q/TE Max	Unit
RESOLUTION			8			8			8			8			Bits
DC ACCURACY Differential Linearity Integral Linearity No Missing Codes	25°C Full 25°C Full Full	I VI I VI VI	Guar	0.6 0.6 anteed	0.75 1.0 1.0 1.2	Guara	0.4 0.4 anteed	0.5 0.75 0.5 1.2	Guara	0.6 0.6 anteed	0.75 1.0 1.0 1.2	Guara	0.4 0.4 anteed	0.5 0.75 0.5 1.2	LSB LSB LSB LSB
INITIAL OFFSET ERROR Top of Reference Ladder Bottom of Reference Ladder Offset Drift Coefficient ANALOG INPUT	25°C Full 25°C Full Full	I VI I VI V		7 6 25	15 18 10 13		7 6 25	15 18 10 13		7 6 25	15 18 10 13		7 6 25	15 18 10 13	$\begin{array}{c} mV\\ mV\\ mV\\ mV\\ \mu V/^{\circ}C \end{array}$
Input Bias Current <sup>1</sup> Input Resistance Input Capacitance Large Signal Bandwidth <sup>2</sup> Analog Input Slew Rate <sup>3</sup>	25°C Full 25°C 25°C 25°C 25°C 25°C	I VI I IIII V V V	25	60 200 16 160 440	200 200 18	25	60 200 16 160 440	200 200 18	25	60 200 16 160 440	200 200 18	25	60 200 16 160 440	200 200 18	μΑ μΑ kΩ pF MHz V/μs
REFERENCE INPUT Reference Ladder Resistance Ladder Temperature Coefficient Reference Input Bandwidth	25°C 25°C	VI V V	40	80 0.25 10	110	40	80 0.25 10	110	40	80 0.25 10	110	40	80 0.25 10	110	Ω Ω/°C MHz
DYNAMIC PERFORMANCE Conversion Rate Aperture Delay Aperture Uncertainty (Jitter) Output Delay $(t_{PD})^{4,5}$ Transient Response <sup>6</sup> Overvoltage Recovery Time <sup>7</sup> Output Rise Time <sup>4</sup> Output Fall Time <sup>4</sup> Output Time Skew <sup>4,8</sup>	25°C 25°C 25°C 25°C 25°C 25°C 25°C 25°C	I V I V I I I V	75 4	100 3.8 15 4.9 8 6.6 3.3 3.0	11 8.0 4.3	75 4	100 3.8 15 4.9 8 8 6.6 3.3 3.0	11 8.0 4.3	75 4	100 3.8 15 4.9 8 8 6.6 3.3 3.0	11 8.0 4.3	75 4	100 3.8 15 4.9 8 8 6.6 3.3 3.0	11 8.0 4.3	MSPS ns ps ns ns ns ns ns ns ns ns ns
ENCODE INPUT Logic "1" Voltage <sup>4</sup> Logic "0" Voltage <sup>4</sup> Logic "1" Current Logic "0" Current Input Capacitance ENCODE Pulsewidth (Low) <sup>9</sup> ENCODE Pulsewidth (High) <sup>9</sup>	Full Full Full 25°C 25°C 25°C	VI VI VI VI V I I I	2.0 2.5 2.5	2.5	0.8 250 400	2.0 2.5 2.5	2.5	0.8 250 400	2.0 2.5 2.5	2.5	0.8 250 400	2.0 2.5 2.5	2.5	0.8 250 400	V V µA pF ns ns
OVERFLOW INHIBIT INPUT 0 V Input Current	Full	VI		200	250		200	250		200	250		200	250	μA
AC LINEARITY <sup>10</sup> Effective Bits <sup>11</sup> In-Band Harmonics DC to 1.23 MHz DC to 9.3 MHz DC to 19.3 MHz Signal-to-Noise Ratio <sup>12</sup> Noise Power Ratio <sup>13</sup>	25°C 25°C 25°C 25°C 25°C 25°C 25°C	V I V V I V	48 46	7.5 55 50 44 47.6 37		48 46	7.5 55 50 44 47.6 37		48 46	7.5 55 50 44 47.6 37		48 46	7.5 55 50 44 47.6 37		Bits dBc dBc dBc dBc dBc dBc
DIGITAL OUTPUT Logic "1" Voltage Logic "0" Voltage	Full Full	VI VI	2.4		0.4	2.4		0.4	2.4		0.4	2.4		0.4	V V
POWER SUPPLY <sup>14</sup> Positive Supply Current (+5.0 V) Supply Current (-5.2 V) Nominal Power Dissipation Reference Ladder Dissipation Power Supply Rejection Ratio <sup>15</sup>	25°C Full 25°C Full 25°C 25°C 25°C	I VI I VI V V I		33 152 955 44 0.85	45 48 179 191 2.5		33 152 955 44 0.85	45 48 179 191 2.5		33 152 955 44 0.8	45 48 179 191 2.5		33 152 955 44 0.8	45 48 179 191 2.5	mA mA mA mW mW mV/V

#### NOTES

<sup>1</sup>Measured with analog input = 0 V.
<sup>2</sup>Measured by FFT analysis where fundamental is -3 dBc.
<sup>3</sup>Input slew rate derived from rise time (10% to 90%) of full-scale step input.
<sup>4</sup>Outputs terminated with two equivalent 'LS00 type loads. (See load circuit.)
<sup>5</sup>Measured from ENCODE into data out for LSB only.
<sup>6</sup>For full-scale step input, 8-bit accuracy is attained in specified time.
<sup>7</sup>Recovers to 8-bit accuracy in specified time, after 150% full-scale input overvoltage.
<sup>8</sup>Output time skew includes high-to-low and low-to-high transitions as well as bit-to-bit time skew differences.

### ABSOLUTE MAXIMUM RATINGS<sup>1</sup>

Positive Supply Voltage (+V <sub>S</sub> ) 6 V
Analog to Digital Supply Voltage Differential $(-V_S)$ 0.5 V
Negative Supply Voltage $(-V_S)$
Analog Input Voltage $-V_S$ to +0.5 V
ENCODE Input Voltage
OVERFLOW INH Input Voltage
Reference Input Voltage $(+V_{REF}, -V_{REF})^2$ 3.5 V to +0.1 V
Differential Reference Voltage 2.1 V
Reference Midpoint Current ±4 mA
Digital Output Current 30 mA
Operating Temperature Range
AD9012AQ/BQ/AJ/BJ $-25^{\circ}$ C to $+85^{\circ}$ C
AD9012SE/SQ/TE/TQ55°C to +125°C
Storage Temperature Range
Junction Temperature <sup>3</sup> 150°C
Lead Soldering Temperature (10 sec) 300°C

#### NOTES

<sup>1</sup>Absolute Maximum Ratings are limiting values, to be applied individually, and beyond which the serviceability of the circuit may be impaired. Functional operability under any of these conditions is not necessarily implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

 $^3\text{Maximum}$  junction temperature (T\_J max) should not exceed 150°C for ceramic and plastic packages:

 $T_J = PD (\theta_{JA}) + T_A$ 

PD  $(\theta_{JC})$  + Tc where:

PD = power dissipation

#### **Recommended Operating Conditions**

	Input Voltage (V)						
Parameter	Min	Nominal	Max				
$\overline{-V_s}$	-5.46	-5.20	-4.94				
$+V_{s}$	+4.75	+5.00	+5.25				
+V <sub>REF</sub>	-V <sub>REF</sub>	0.0	+0.1				
-V <sub>REF</sub>	-2.1	-2.0	$+V_{REF}$				
Analog Input	-V <sub>REF</sub>		$+V_{REF}$				

- <sup>9</sup>ENCODE signal rise/fall times should be less than 30 ns for normal operation.
  <sup>10</sup>Measured at 75 MSPS ENCODE rate. Harmonic data based on worst-case harmonics.
- <sup>11</sup>Analog input frequency = 1.23 MHz.
- <sup>12</sup>RMS signal to rms noise, including harmonics with 1.23 MHz. Analog input signal.
- <sup>13</sup>NPR measured @ 0.5 MHz. Noise source is 250 mW (rms) from 0.5 MHz to 8 MHz.
- $^{14}\text{Supplies}$  should remain stable within  $\pm5\%$  for normal operation.
- $^{15}\text{Measured}$  at –5.2 V ±5% and +5.0 V ±5%.

Specifications subject to change without notice.

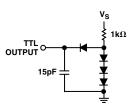


Figure 1. Load Circuit

### EXPLANATION OF TEST LEVELS Test Level

- I 100% production tested.
- II 100% production tested at 25°C, and sample tested at specified temperatures. AC testing done on sample basis.
- III Sample tested only.
- IV Parameter is guaranteed by design and characterization testing.
- V Parameter is a typical value only.
- VI All devices are 100% production tested at 25°C. 100% production tested at temperature extremes for extended temperature devices; guaranteed by design and characterization testing for industrial devices.

Device Linearity		Temperature Ranges	Package Options*		
AD9012AQ	0.75 LSB	–25°C to +85°C	Q-28		
AD9012BQ	0.50 LSB	-25°C to +85°C	Q-28		
AD9012AJ	0.75 LSB	-25°C to +85°C	J-28A		
AD9012BJ	0.50 LSB	-25°C to +85°C	J-28A		
AD9012SQ	0.75 LSB	–55°C to +125°C	Q-28		
AD9012SE	0.75 LSB	–55°C to +125°C	E-28A		
AD9012TQ	0.50 LSB	–55°C to +125°C	Q-28		
AD9012TE	0.50 LSB	–55°C to +125°C	E-28A		

\*E = Leadless Ceramic Chip Carrier; J = Ceramic Leaded Chip Carrier; Q = Cerdip.

#### CAUTION\_

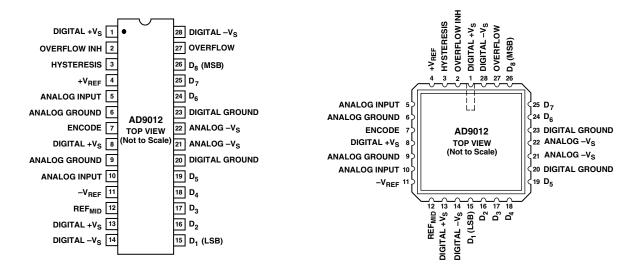
ESD (electrostatic discharge) sensitive device. Electrostatic charges as high as 4000 V readily accumulate on the human body and test equipment and can discharge without detection. Although the AD9012 features proprietary ESD protection circuitry, permanent damage may occur on devices subjected to high energy electrostatic discharges. Therefore, proper ESD precautions are recommended to avoid performance degradation or loss of functionality.



 $<sup>^{2}+</sup>V_{REF} \ge -V_{REF}$  under all circumstances.

Pin No.	Mnemonic	Description								
11 12	DIGITAL +V <sub>S</sub> OVERFLOW INH	One of Three Positive Digital Supply Pins (Nominally 5.0 V) OVERFLOW INH BIT controls the data output coding for overvoltage inputs (AIN $\geq$ + V <sub>REI</sub>								
		Analog InputOverflow Enabled (Floating) of D1D2 D3D4D5D6D7D8Overflow Inhibited (GND) of D1D2D3D4D5D6D7D8								
		$V_{IN}$ + $V_{REF}$	1 0 0 0 0 0 0 0 0	0 1 1 1 1 1 1 1 1 1						
		$V_{IN} < +V_{REF}$	0 X X X X X X X X	0 X X X X X X X X X						
3	HYSTERESIS	•	rol voltage varies the comparator hyste to $-2.2$ V at the hysteresis control pin							
14	+V <sub>REF</sub>									
15	ANALOG INPUT		The Most Positive Reference Voltage for the Internal Resistor Ladder One of Two Analog Input Pins. Both analog input pins should be connected together.							
16	ANALOG GROUND									
17	ENCODE		One of Two Analog Ground Pins. Both analog ground pins should be connected together. TTL Level ENCODE Command Input. ENCODE is rising edge sensitive.							
18	DIGITAL $+V_8$		One of Three Positive Digital Supply Pins (Nominally +5.0 V)							
19	ANALOG GROUND	One of Two Analog Ground Pins. Both analog ground pins should be connected together.								
10	ANALOG INPUT	One of Two Analog Input Pins. Both analog inputs should be connected together.								
11	-V <sub>REF</sub>	The Most Negative Reference Voltage for the Internal Resistor Ladder								
12	REF <sub>MID</sub>	The Midpoint Tap on the Internal Resistor Ladder								
13	DIGITAL +V <sub>S</sub>	One of Three Positive Digital Supply Pins (Nominally +5.0 V)								
14	DIGITAL -V <sub>S</sub>	One of Two Negative Digital Supply Pins (Nominally –5.2 V). Both digital supply pins should be connected together.								
15	$D_1$ (LSB)	Digital Data Output. $D_1$ (LSB) is the least significant bit of the digital output word.								
16-19	$D_2 - D_5$	Digital Data Output								
20	DIGITAL GROUND	One of Two Digital Ground Pins. Both digital grounds pins should be connected together.								
21, 22	ANALOG –V <sub>S</sub>	One of Two Negative Analog Supply Pins (Nominally –5.2 V). Both analog supply pins should be connected together.								
23	DIGITAL GROUND	One of Two Digital Ground Pins. Both digital ground pins should be connected together.								
24, 25	$D_6, D_7$	Digital Data Output								
26	$D_8$ (MSB)	Digital data output $D_8$ (MSB) is the most significant bit of the digital output word.								
27	OVERFLOW		put. Logic HIGH indicates an input or							
			is enabled (overflow enabled, floating)							
28	DIGITAL –Vs	One of Two Negati connected together.		2 V). Both digital supply pins should be						

### PIN CONFIGURATIONS



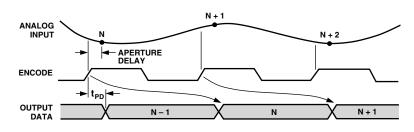


Figure 2. Timing Diagram

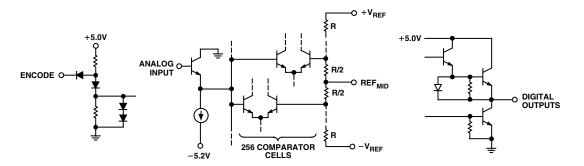
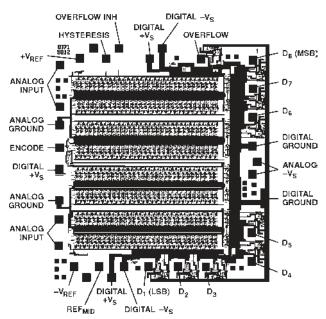


Figure 3. Input Output Circuits

## DIE LAYOUT AND MECHANICAL INFORMATION



Die Dimensions 111 mils	123 mils 15 mils ( $\pm 2$ ) mils
Pad Dimensions	4 mils 4 mils
Metallization	Gold
Backing	None
Substrate Potential	$-V_S$
Passivation	Nitride
Die Attach	Gold Eutectic (Ceramic)
	Epoxy (Plastic)
Bond Wire 1 mil to 1.3	3 mil Gold; Gold Ball Bonding

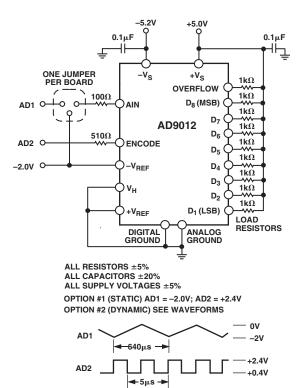


Figure 4. Burn-In Diagram

### APPLICATION INFORMATION

The AD9012 is compatible with all standard TTL logic families. However, to operate at the highest ENCODE rates, the supporting logic around the AD9012 will need to be equally fast. Two possible choices are the AS and the ALS families. Whichever of the TTL logic families is used, special care must be exercised to keep digital switching noise away from the analog circuits around the AD9012. The two most critical items are the digital supply lines and the digital ground return.

The input capacitance of the AD9012 is an exceptionally low 16 pF. This allows the use of a wide range of input amplifiers, both hybrid and monolithic. To take full advantage of the 160 MHz input bandwidth of the AD9012, a hybrid amplifier such as the AD9610 will be required. For those applications that do not require the full input bandwidth of the AD9012, some of the more traditional monolithic amplifiers, such as the AD846, should work very well. Overall performance with monolithic amplifiers can be improved by inserting a 40  $\Omega$  resistor in series with the amplifier output.

The output data is buffered through the TTL compatible output latches. In addition to the latch propagation delay ( $t_{PD}$ ), all data is delayed by one clock cycle before becoming available at the outputs. Both the analog-to-digital conversion cycle and the data transfer to the output latches are triggered on the rising edge of the TTL compatible ENCODE signal (see Figure 2).

The AD9012 also incorporates a HYSTERESIS control pin that provides from 0 mV to 10 mV of additional hysteresis in the comparator input stages. Adjustments in the HYSTERESIS control voltage may help to improve noise immunity and overall performance in harsh environments.

The OVERFLOW INH pin of the AD9012 determines how the converter handles overrange inputs (AIN  $\geq$  + V<sub>REF</sub>). In the "enabled" state (floating at –5.2 V), the OVERFLOW INH output will be at logic HIGH and all other outputs will be at logic LOW for overrange inputs (return-to-zero operation). In the "inhibited" state (tied to ground), the OVERFLOW INH output will be at logic LOW for overrange inputs, and all other digital outputs will be at logic HIGH (nonreturn-to-zero operation).

The AD9012 provides outstanding error rate performance. This is due to tight control of comparator offset matching and a fault tolerant decoding stage. Additional improvements in error rate are possible through the addition of hysteresis (see HYSTERESIS control pin). This level of performance is extremely important in fault sensitive applications, such as digital radio (QAM).

Dramatic improvements in comparator design and construction give the AD9012 excellent dynamic characteristics, namely SNR (signal-to-noise ratio). The 160 MHz input bandwidth and low error rate performance give the AD9012 an SNR of 47 dB with a 1.23 MHz input. High SNR performance is particularly important in broadcast video applications where signals may pass through the converter several times before the processing is complete. Pulse signature analysis, commonly performed in advanced radar receivers, is another area that is especially dependent on high quality dynamic performance.

### LAYOUT SUGGESTIONS

Designs using the AD9012, such as all high speed devices, must follow a few basic layout rules to ensure optimum performance. Essentially, these guidelines are meant to avoid many of the problems associated with high speed designs. The first requirement is for a substantial ground plane around and under the AD9012. Separate ground plane areas for the digital and analog components may be useful, but the separate grounds should be connected together at the AD9012 to avoid the effects of "ground loop" currents.

The second area that requires an extra degree of attention involves the three reference inputs,  $+V_{REF}$ ,  $REF_{MID}$ , and  $-V_{REF}$ . The  $+V_{REF}$  input and the  $-V_{REF}$  input should both be driven from a low impedance source (note that the  $+V_{REF}$  input is typically tied to analog ground). A low drift amplifier should provide satisfactory results, even over an extended temperature range. Adjustments at the  $REF_{MID}$  input may be useful in improving the integral linearity by correcting any reference ladder skews.

The reference inputs should be adequately decoupled to ground through 0.1  $\mu$ F chip capacitors to limit the effects of system noise on conversion accuracy. The power supply pins must also be decoupled to ground to improve noise immunity; 0.1  $\mu$ F and 0.01  $\mu$ F chip capacitors should be very effective.

The analog input signal is brought into the AD9012 through two separate input pins. It is very important that the two input pins be driven symmetrically with equal length electrical connections. Otherwise, aperture delay errors may degrade converter performance at high frequencies.

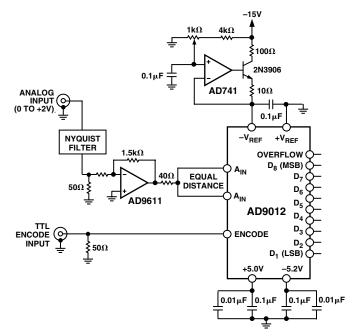


Figure 5. Typical Application

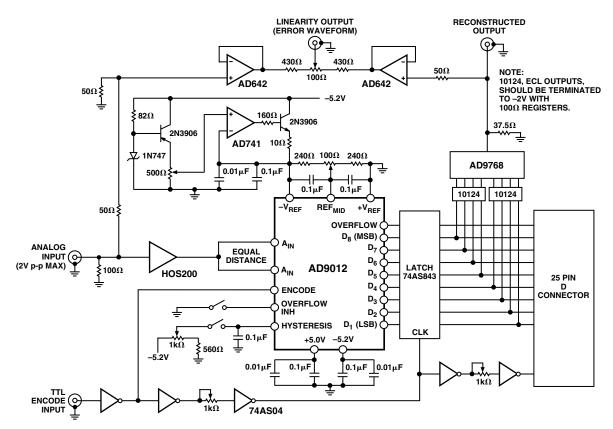


Figure 6. Evaluation Circuit

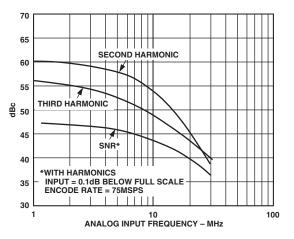
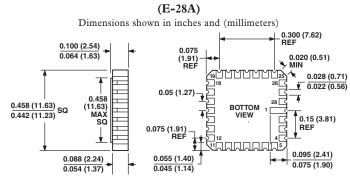


Figure 7. Dynamic Performance

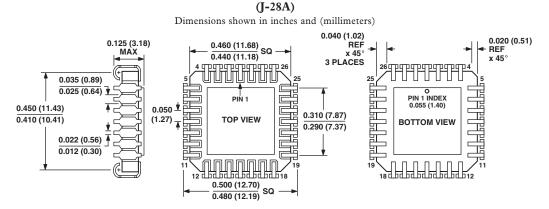
#### **OUTLINE DIMENSIONS**

### 28-Terminal Ceramic Leadless Chip Carrier [LCC]

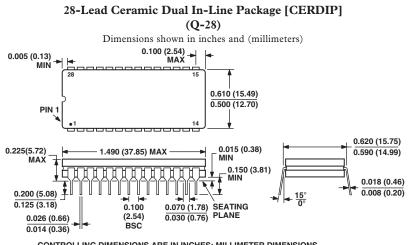


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28-Lead Ceramic Leaded Chip Carrier – J-Formed Lead [JLCC]



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## **Revision History**

#### Location

5/03—Data Sheet changed from REV. E to REV. F. Changes to OUTLINE DIMENSIONS ..... Page

C00547-0-5/03(F)

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